

TO-252 Pin Configuration

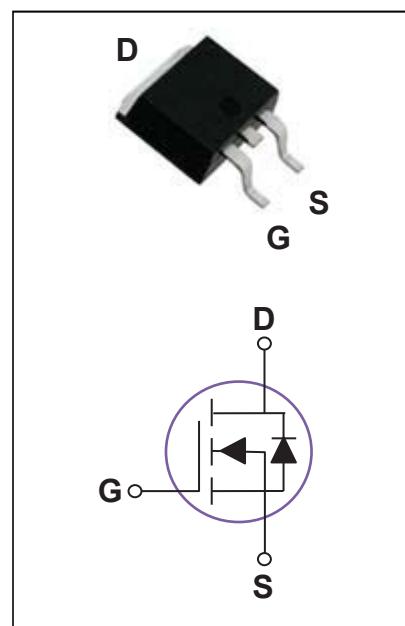
BVDSS	RDS(ON)	ID
30V	4.1mΩ	74A

Features

- 30V, 74A, $RDS(ON) = 4.1\text{m}\Omega$ @ VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- Networking
- Load Switch
- LED applications


MAXIMUM RATINGS AND CHARACTERISTICS

@ 25°C Ambient Temperature (unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	VDS	30	V
Gate-Source Voltage	VGS	±20	V
Drain Current – Continuous (TC=25°C)	ID	74	A
Drain Current – Continuous (TC=100°C)		46.8	A
Drain Current – Pulsed ¹	IDM	296	A
Single Pulse Avalanche Energy ²	EAS	115	mJ
Single Pulse Avalanche Current ²	IAS	48	A
Power Dissipation (TC=25°C)	PD	54.3	W
Power Dissipation – Derate above 25°C		0.44	W/°C
Storage Temperature Range	TSTG	-50 to +150	°C
Operating Junction Temperature Range	TJ	-50 to +150	°C

Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to ambient	R _{θJA}	---	62	°C/W
Thermal Resistance Junction to Case	R _{θJC}	---	2.3	°C/W

MOSFET ELECTRICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ unless otherwise specified

Off Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$		Reference to 25°C , $I_D=1\text{mA}$	---	0.03	---	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}$, $I_D=15\text{A}$	---	3.4	4.1	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=10\text{A}$	---	4.7	6	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1.0	1.6	2.5	V
$V_{\text{GS}(\text{th})}$ Temperature Coefficient			---	-4.17	---	$\text{mV}/^\circ\text{C}$
Forward Transconductance	g_{fs}	$V_{\text{DS}}=10\text{V}$, $I_D=3\text{A}$	---	10	---	S

Dynamic and switching Characteristics

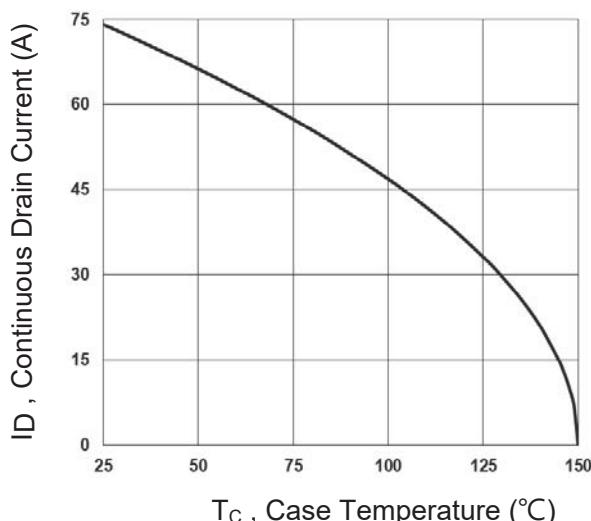
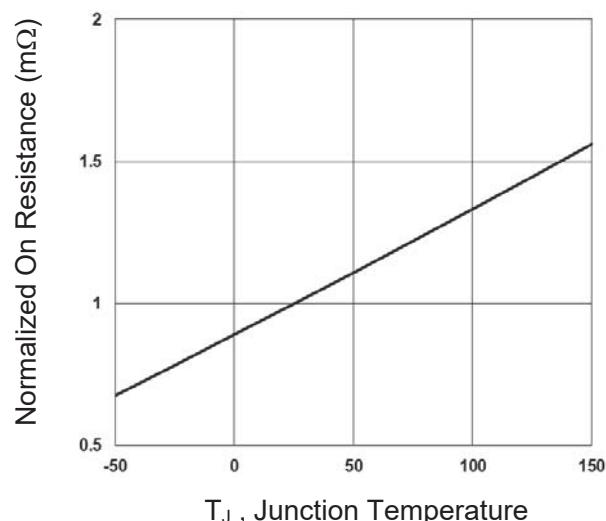
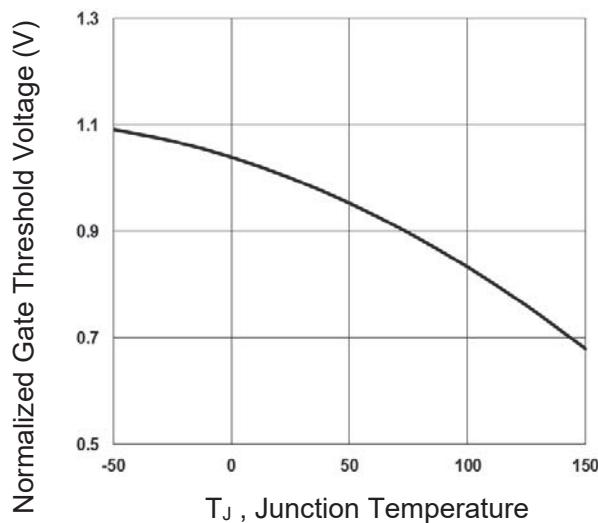
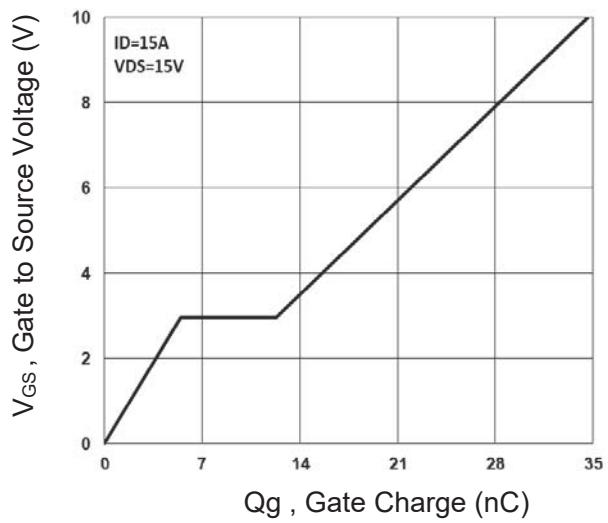
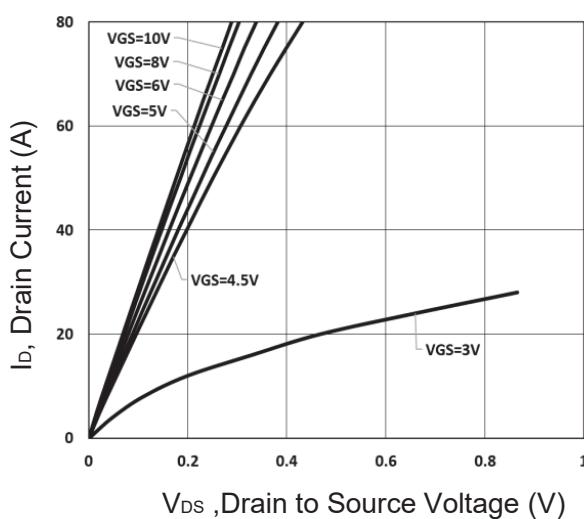
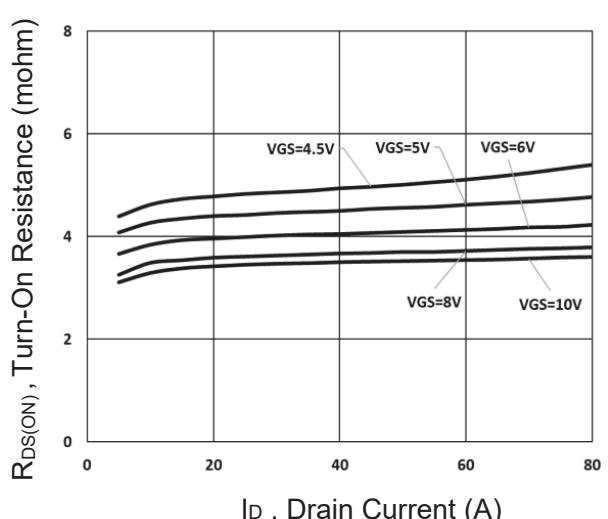
Total Gate Charge ^{3, 4}	Q_g	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=15\text{A}$	---	34.6	70	nC
Gate-Source Charge ^{3, 4}	Q_{gs}		---	5.5	11	
Gate-Drain Charge ^{3, 4}	Q_{gd}		---	6.8	13	
Turn-On Delay Time ^{3, 4}	$T_{\text{d}(\text{on})}$	$V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3.3\Omega$ $I_D=1\text{A}$	---	9.7	20	ns
Rise Time ^{3, 4}	T_r		---	15.8	31	
Turn-Off Delay Time ^{3, 4}	$T_{\text{d}(\text{off})}$		---	37.4	75	
Fall Time ^{3, 4}	T_f		---	12	24	
Input Capacitance	C_{iss}		---	1910	3800	pF
Output Capacitance	C_{oss}	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	300	600	
Reverse Transfer Capacitance	C_{rss}		---	230	460	
Gate resistance	R_g	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $F=1\text{MHz}$	---	1.14	---	Ω

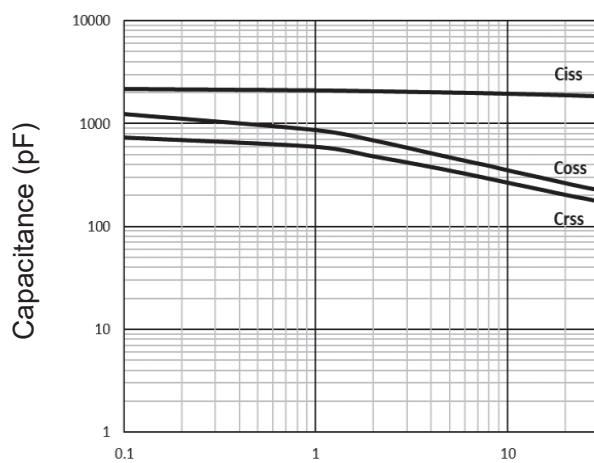
Drain-Source Diode Characteristics and Maximum Ratings

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_s	$V_G=V_D=0\text{V}$, Force Current	---	---	74	A
Pulsed Source Current	I_{SM}		---	---	148	A
Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V
Reverse Recovery Time	t_{rr}		---	2.33	---	us
Reverse Recovery Charge	Q_{rr}	$T_J=25^\circ\text{C}$	---	48.9	---	μC

Note :

- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=48\text{A}$, $R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.
- The data tested by pulsed, pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
- Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. TC

Fig.2 Normalized RDS(ON) vs. TJ

Fig.3 Normalized V_{th} vs. TJ

Fig.4 Gate Charge Characteristics

Fig.5 Typical Output Characteristics

Fig.6 Turn-On Resistance vs. ID



V_{DS}, Drain to Source Voltage (V)

Fig.7 Capacitance Characteristics

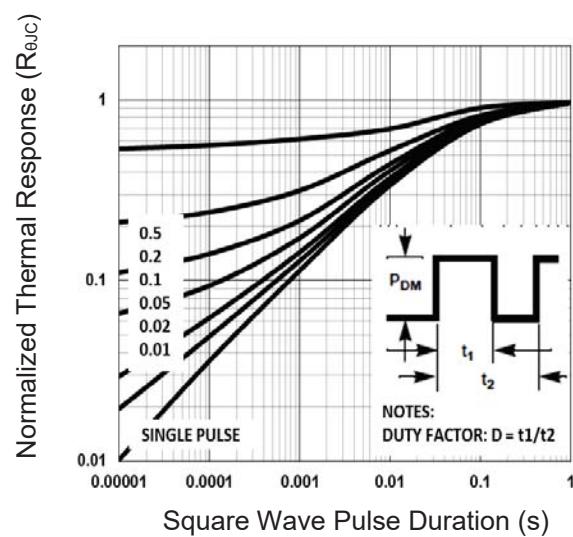
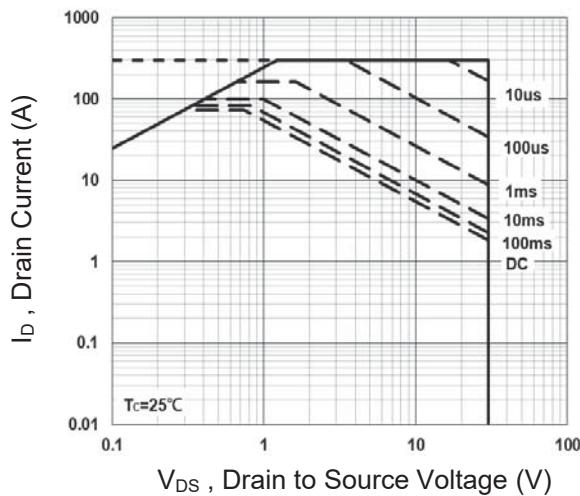


Fig.8 Normalized Transient Impedance



V_{DS}, Drain to Source Voltage (V)

Fig.9 Maximum Safe Operation Area

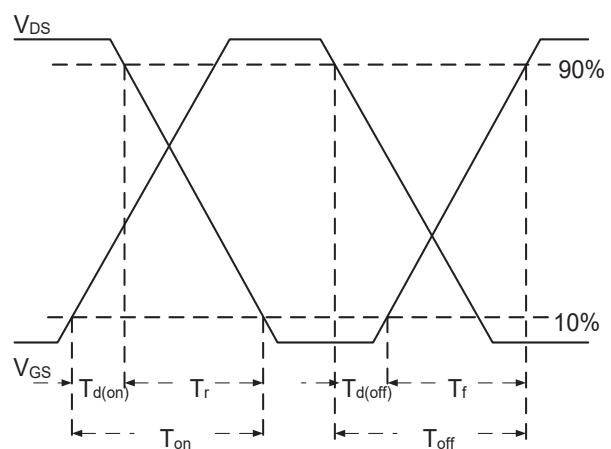


Fig.10 Switching Time Waveform

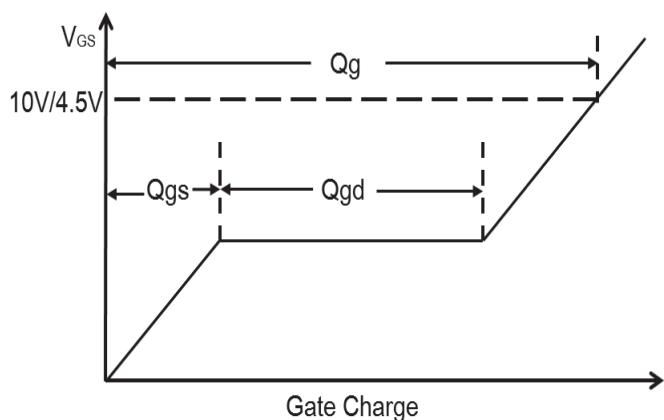
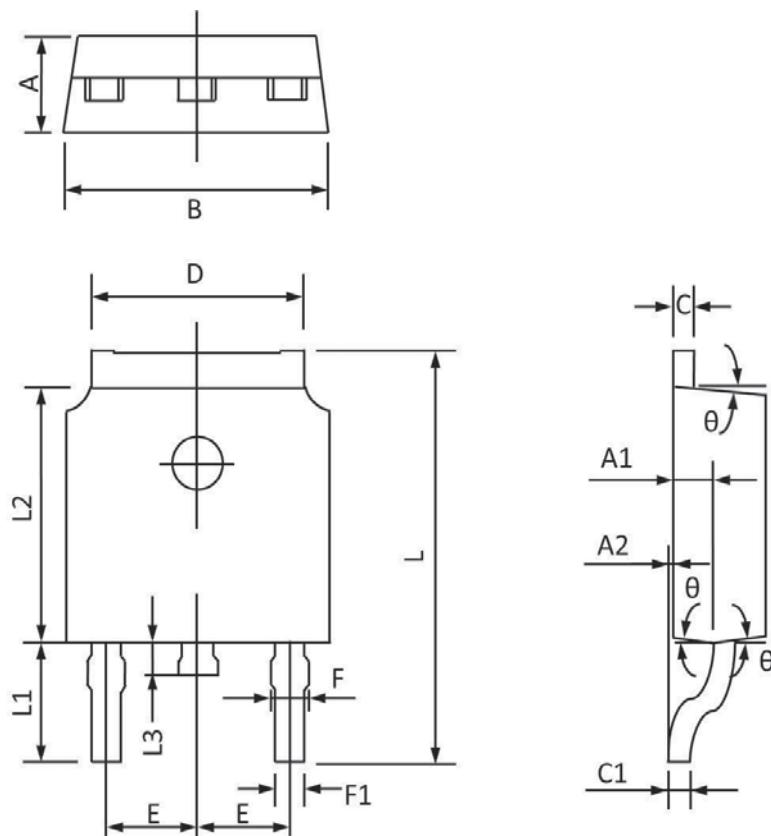


Fig.11 Gate Charge Waveform

TO-252 PACKAGE INFORMATION


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.400	2.200	0.094	0.087
A1	1.110	0.910	0.044	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.400	0.268	0.252
C	0.580	0.450	0.023	0.018
C1	0.580	0.460	0.023	0.018
D	5.500	5.100	0.217	0.201
E	2.386	2.186	0.094	0.086
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.400	0.244	0.213
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°